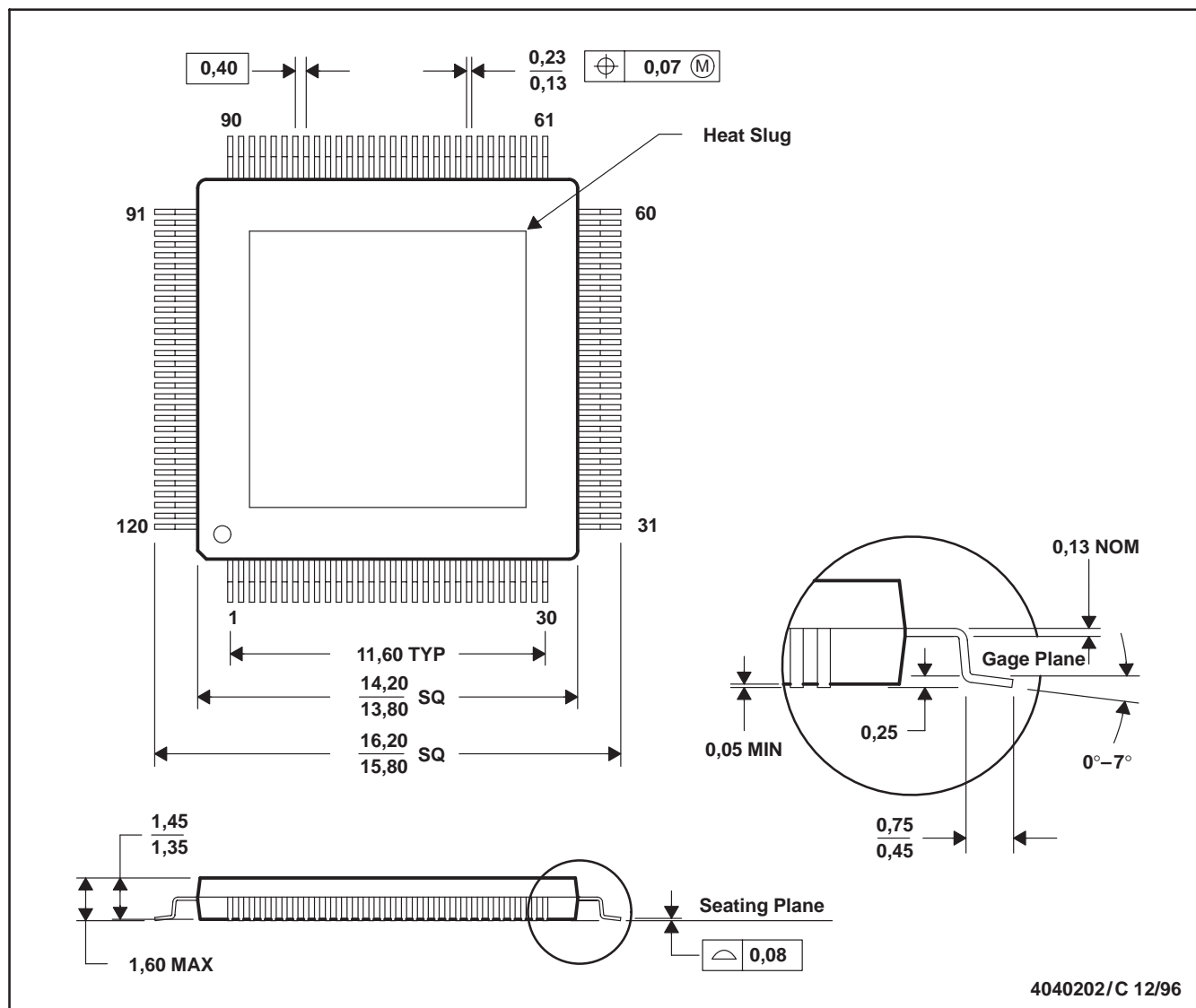


## PCB (S-PQFP-G120)

## PLASTIC QUAD FLATPACK (DIE-DOWN)



- NOTES: A. All linear dimensions are in millimeters.  
 B. This drawing is subject to change without notice.  
 C. Thermally enhanced molded plastic package with a heat slug (HSL)  
 D. Falls within JEDEC MS-026

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